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TITLE: Sputtering equipment

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ABSTRACTED-PUB-NO: KR2001009208A

BASIC-ABSTRACT:

NOVELTY - A sputtering equipment is provided to clear cumbersomeness during the process and reduce economical losses by adjusting heights of first and second vertical pillars which comprises a sputtering equipment, thereby freely controlling a distance between a substrate and a target.

DETAILED DESCRIPTION - A sputtering equipment consists of a substrate (100); a

closed curve shaped **bellows** pipe (130a) which is put on a certain part of the substrate (100), and on which a wafer is practically mounted; a target supporting plate (110) which is located on the substrate (100) so as to be in an opposite direction to the substrate (100), and on which a metal target (160) is mounted; an adjusting screw shaped first vertical pillar (120) which is formed along its inside edge line so as to surround an inner space defined by the target supporting plate (110) and the substrate (100), and designed so that a plate type pillar (120b) is put on at center area, and a height of the pillar can be adjusted at both edges; a plate type pillar shaped second vertical pillar (130); a first shield (170a) formed along the target supporting plate (110) near the target (160) so that surrounding area of the metal target (160) is surrounded; a second shield (170b) positioned along upper part outside the closed curve shaped **bellows** pipe (130a); and a third shield (170c) formed along inside the pillar right over the **bellows** pipe (130a) which comprises the second vertical pillar (130) so as to be put between the first and second shields (170a,170b).

CHOSEN-DRAWING: Dwg.1/10

TITLE-TERMS: SPUTTER EQUIPMENT

DERWENT-CLASS: M13

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